

● DATE
09-10 May

● LOCATION
Le Meridien Taipei

International Semiconductor Executive Summit

TAIWAN 2023

Shaping the Future of the Semiconductor Industry: Technical Needs and Opportunities to Drive Long-term Growth and Innovation in Semiconductor Manufacturing Industry

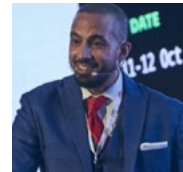
Day 1 - 9th May

08:00 - 08:50 Registration

09:00 - 09:20

ISES WELCOME ADDRESS

Salah Nasri
President & Managing Director



HPC Session

09:20 - 09:50

AMD
Bill En
CVP Foundry Technology and Operations

- Topic: Innovation to Enable More Compute from Each Transistor



KEYNOTE SPEAKER

EVENT AGENDA



DATE

09-10 May



LOCATION

Le Meridien Taipei

09:50 - 10:20

Micron

Steve Pawlowski

CVP Advanced Memory Systems

- Topic: Now is the Time to Re-imagine Memory Centric Computing



KEYNOTE
SPEAKER

10:20 - 11:20

COFFEE BREAK SPONSORED BY CNW

Business Meeting 1 & 2,
Networking and Coffee Break

Advanced Packaging Session

11:20 - 11:50

TSMC

Kam Lee

Senior Director, Deputy Head
of TSMC Advanced Packaging
Technology and Service

- Topic: Unleash Product Innovations with 3DFabric



KEYNOTE
SPEAKER

11:50 - 12:20

Samsung Electronics

Dr. Seungwook Yoon

CVP Business Development Team, AVP

- Topic: Heterogeneous Integration Platform for Next Generation Computing



KEYNOTE
SPEAKER

12:20 - 12:40

ASE

Dr. CP Hung

CVP RD

- Topic: New Energy to Semiconductor - Heterogeneous Integration Packaging



● DATE
09-10 May

● LOCATION
Le Meridien Taipei

12:40- 13:40

Buffet Lunch

13:45 - 14:05

Advantest

Michael Chang

VP & GM, Advantest Cloud Solutions

- Topic: A 360 View of Semiconductor Test from AI and Security Perspective



14:05 - 14:15

Adeia

Abul Nuruzzaman

VP of Sales

- Topic: Hybrid Bonding: Innovation to Adoption



Automotive and Power Semiconductor Panel Session

14:15 - 14:35

GaN Systems

Stephen Coates

GM & VP Global Operations

- Topic: GaN is Accelerating e-Mobility



EVENT AGENDA



DATE

09-10 May



LOCATION

Le Meridien Taipei



PANEL DISCUSSION

14:40 - 15:20

Opportunities and Challenges for Power Semiconductor Industry. How can Taiwan Supply Chain Help?



MODERATOR

GaN Systems

Andy Chuang

VP Business Development



PANELISTS

Amkor

Walter Chen

SVP Greater China Sales & Marketing



Cyntec

Ian Chan

CTO & Managing Director



GaN Systems

Stephen Coates

GM & VP Global Operations



ITRI

Dr. Wei-Chung Lo

Deputy General Director of
Electronic and Optoelectronic
System Research Laboratories



● DATE
09-10 May

● LOCATION
Le Meridien Taipei

15:20 - 16:20

COFFEE BREAK SPONSORED BY CNW
Business Meeting 3 & 4,
Networking and Coffee Break

Equipment and Service Supplier Session

16:20 - 16:30

Airspace

Aziza Dad

Sector VP

- Topic: A 360 View of Digitalisation of Supply Chain - Using Latest Technology to Improve Logistics



16:30 - 16:45

Onto Innovation

Dr. Monita Pau

Director Strategic Marketing,
Advanced Packaging

- Topic: Process Control Challenges in Packaging for High Performance Computing Applications



16:45 - 16:55

ASMPT

Nelson Fan

VP, Head of KPU Advanced Packaging

- Topic: Challenges and Solution of FLI Technologies in various HI Packaging Architectures



09-10 May

Le Meridien Taipei

16:55 - 17:05

MKS | Atotech**Dr. Christian Ohde**

Global Product Director SC/FEC

- Topic: Technology Pushes Limits - How New Plating Solutions Enable the Semiconductor Devices of Tomorrow



17:05 - 17:10

SUSS MicroTec**Thomas Schmidt**

Product Manager, Bonder Division

- Topic: 3DIC W2W and D2W Hybrid Bonding



17:10 - 17:15

Lam Research**Elpin Goh**

Senior Director Business Development, Specialty Technologies

- Topic: Deep Reactive Ion Etch - Enabling Advanced Specialty Technologies and Packaging Applications



17:15 - 17:20

Evatec**Ralph Zoberbier**

SVP & Head of Business Unit Advanced Packaging

- Topic: Thinfilm Technology for Heat Dissipation Layers in HPC Applications



● DATE
09-10 May

● LOCATION
Le Meridien Taipei

17:20 - 18:20 Cocktail Reception

18:20 - 18:30 Dinner Check-in

18:30 - 21:00

**GALA DINNER SPONSORED BY
ONTO INNOVATION**

Welcome Speech

Onto Innovation

Vincent Wang

VP of Greater China





09-10 May



Le Meridien Taipei

Day 2 - 10th May

08:00 - 08:40

Registration

8:40 - 9:00

OPENING SPEECH

ITRI

Dr. Ming-Der Shieh

CTO of Electronic and
Optoelectronic System Research
Laborations (EOSL)

- Topic: Challenges & Opportunities of LLM and Generative AI: A Hardware Perspective



Metaverse Session

9:00 - 9:30

Meta

Dr. Ofer Shacham

VP, Head of Silicon, at Meta
Reality Labs

- Topic: How the Semiconductor Industry Is Poised to Enable the Metaverse

KEYNOTE
SPEAKER

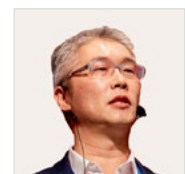
9:30 - 9:50

Qualcomm

Patrick Chiang

Senior Director Technical Marketing

- Topic: Inspiring a new reality with XR



● DATE
09-10 May

● LOCATION
Le Meridien Taipei

9:50 - 10:10

Aspeed
CJ Hsieh
COO

• Topic: Turning Metaverse to Photorealistic Digital Twins for Driving Smart Factory Innovations



10:10 - 11:10

COFFEE BREAK SPONSORED BY CNW
Business Meeting 5 & 6,
Networking and Coffee Break

11:10 - 11:30

UMC
Steven Hsu
VP Technology Development

• Topic: Display Technology for Metaverse - A Foundry's Perspective



11:30 - 11:50

PlayNitride
Dr. Charles Li
CEO & Co-Founder

• Topic: Opportunities and Challenges for MicroLED Display



11:50 - 13:10

Buffet Lunch



09-10 May



Le Meridien Taipei

AI Session

13:10 - 13:30

Mediatek**Dr. Bor-Sung Liang**Senior Director Strategic
Technology Exploration Platform

- Topic: AI Computing in Large-Scale Era - The Golden Age of AI and IC

**KEYNOTE
SPEAKER**

13:30 - 13:50

Skymizer**Luba Tang**

CEO

- Topic: From Hyperscale Models to Heterogeneous SoCs: Industrializing Neural Network Deployment with ONNC



13:50 - 14:10

Etron**Dr Justin Chueh**Director Monolithic and
Heterogeneous Integration
Department

- Topic: Unleashing the Power of AI: Opportunities and Challenges Ahead



● DATE
09-10 May

● LOCATION
Le Meridien Taipei

14:10 - 15:10

COFFEE BREAK SPONSORED BY CNW
Business Meeting 7,
Networking and Coffee Break

● FINALE PANEL DISCUSSION:
15:10 - 15:55

Future of Taiwanese Semiconductor Supply Chain: Collaborations with International Partners

● MODERATOR

ITRI

Ray Yang

Consulting Director of Industry,
Science and Technology
International Strategy Center
(ISTI)



● PANELISTS

AMD

Bill En

CVP Foundry Technology and
Operations



Applied Materials

Albert Lan

Global Packaging Account TD Head



EVENT AGENDA



DATE

09-10 May



LOCATION

Le Meridien Taipei

Goldman Sachs

Bruce Lu

VP Asia Technology



NYCU

Dr. Kuan-Neng Chen

Chair Professor



Qualcomm

Jian Zhang

VP Product Test Engineering



Market Trend Session

16:00 - 16:20

Neumonda / APIS4

Marco Mezger

COO & Executive Vice President /
CEO & Founder

- Topic: Navigating the Dynamic Memory Market: Trends and Insights



16:20 - 16:30

CLOSING ADDRESS

Salah Nasri

President & Managing Director

